TI Developer Conference March 7-9, 2007 • Dallas, TX

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RapidIO Rev 2.0 for Next-Generation Communication and Embedded Systems

Travis Scheckel Texas Instruments



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Rev 2.0 New Features

- Two major areas of concentration
 - New Higher Performance Physical Layer
 - Extending bandwidth with available SerDes technology
 - Significant Data Plane Enhancements
 - Offering carrier grade data fabric performance
- Additional work to standardize Encapsulation

 Early focus on Ethernet

New Serial Physical Layer Feature Overview

- Rev 2.0 is backwards compatible with Rev 1.3
- Link width options are 1x, 2x, 4x, 8x and 16x
- Signaling rates of 1.25, 2.5, 3.125, 5.0 and 6.25
 Gbaud
- AC electrical specs
 - Speeds < 3.5 Gbaud are based on XAUI</p>
 - Speeds > 3.5 Gbaud are based on OIF
- Data is scrambled and 8b/10b encoded
- Hot plug support at the electrical level
- Introduction of new functionality in control symbol and Idle pattern
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Serial Features Continued...

- Baud rates of 1.25, 2.5 or 3.125 Gbaud
 - Long Reach: 50 cm channel length with 2 connectors
 - Short Reach: 20 cm channel length with 1 connector
- Baud rates of 5.0 and 6.25 Gbaud
 - Long Reach: 100 cm channel length with 2 connectors
 - Medium Reach: 60 cm channel length with 2 connectors
 - Short Reach: 20 cm channel length with 1 connector
- Support for DFE based receivers increases channel choices
- Supports StatEye channel compliance testing
 - Valuable for closed data eye evaluation

New Control Symbol and Idle



- Control symbol provides better CRC protection for DFE based receivers
- Control symbol allows for virtual output queuing
 - Backpressure indication mechanism
- Idle provides auto detection of
 - Lane polarity, port width/lane number, data rate capabilities
- Idle provides equalizer training and mechanism for RX to adjust TX emphasis settings
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Data Plane Feature Overview

- New Data Streaming Packet Format
- Addition of Virtual Channels (VCs) to Serial Physical Layer
- Virtual Output Queue (VoQ) Spec
- New Endpoint Flow Control Arbitration
- New Traffic Management Spec

Data Streaming Support

- Type 9 packet format for streaming data
- Supports up to 64-K PDU sizes using selectable MTU size and SAR
- Supports thousands of data streams between endpoints, as well as, concurrent PDUs
- Introduces COS support with hundreds of traffic classes
- Supports multicast
- Supports lossy transactions
- Can be used for encapsulation of any arbitrary protocol Minds in Motion

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Endpoint

Endpoint

Virtual Channels

- Allows physical channel to be subdivided into independently managed subchannels
 - No ordering guaranteed between VCs
 - Individual link layer flow control and buffers for 9 VCs
- Allows reserving of bandwidth and Quality of Service (QoS) on subchannel granularity
 - Scheduling is Implementation defined
- Introduces Continuous Traffic to existing Reliable Traffic
 - Reliable traffic uses VC0, priority based
 - VC1 VC8 can support Continuous Traffic



Increases utilization of the switch fabric

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Virtual Output Queuing

- Method that provides physical layer status messages to communicate congestion status of downstream device's ports.
- Greatly reduces head-of-line (HOL) blocking, increasing fabric performance
- Utilizes the new extended control symbol



VoQ Looks Forward



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Mode 0 = v1.3 based traffic Mode 1 = VC based Mode 2 = VC + VoQ

Courtesy of Chunhua Hu, Erlang Technologies

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Flow Control Options

- Goal of flow control is to prevent traffic from being admitted to fabric if resources aren't available at the destination
- Course grain flow control using Type 7 packets allows arbitration of segmentation contexts at the PDU level
- Fine Grain flow control uses Type 9 extended header which allows receiver to throttle back the transmitter based on COS and stream based queues.

Encapsulation

- Specification of Encapsulation over RapidIO
 - Standard is agnostic of encapsulated protocol
 - Standard supports existing devices which support Message (type 11) packets
 - Standard also supports Data Streaming (Type 9) packets
 - Does not support memory mapped transfers
- Defines Software and Hardware Methodology for Advertising participation, managing the session, and actual packet encapsulation formats

Summary

- Higher Bandwidth, Maintaining Low Overhead
- Complete Set of Transactions
 - I/O
 - Messaging
 - Globally Shared Memory
 - Streaming Data
- Carrier Grade Data Fabric Performance
 - Deterministic Latency
 - Quality of Service
 - End to End Data Management
- Standardization of Encapsulation

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Some experiences from actually using sRIO

Dr Peter Olanders Ericsson AB



TAKING YOU FORWARD

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Testbeds

- Ericsson has lately developed a number
- of testbeds, as
- HSDPA (2003 / 2004)
- HSUPA (2005)
- eHSPA (a, b, ..)
- MIMO (demonstrated CTIA 2006)
- MBMS (-"-)
- LTE (demo at 3GSM 2007)
- (non exhaustive list!)

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Testbeds and purpose

- Demonstrate high data rates in mobile systems Mbit/s
- HSDPA 5-15 DL
- HSUPA 2-5 UL
- eHSPA 25 / 10 -> 50/20 ->??
- LTE 100 / 50 ++
- MBMS: Multimedia Broadcast Multicast service



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We all start from somewhere

- First building practise
- Propretiary format
- In a PC case
- It worked fine
- But hardly flexible, re-usable, scalable



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TI Developer ConferenceLong term vision, 2003



 Note: this is for testbeds, not for products!
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 Image: Image

High data rate RBS testbed

- Clearly, not an Ericsson product
- It is a testbed!
- sRIO in all digital parts





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Mezzanine level

DSPs & some glue and comms

- AMC
- Can be used in ATCA and mTCA
- Quite generic



Note: testbed!

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Life is full of problems ...



- Contact or lack thereof
- In fact, for hot-swap, it should be the broken connectors (left).

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An UE was developed as well

- Not really handheld
- But mobile
- A complete system
- Possible to test system
 mobile performance



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sRIO experiences - testbeds

- More flexible than anticipated
- Easy to use
- Hot-swap works fine
- BB radio interface sRIO based!
- Interoperability, as always

sRIO use in testbeds

- Every user set up his/her way of using a technology; a protocol
- We used e.g. a combination of SWRITE and NWRITE DOORBELL
- Maintenance write/read for system configuration and monitoring
- Interoperability?

Future demands on sRIO

- Higher data rates
 (3 -> 6 -> 10 -> ..)
- 2x for cost & efficiency
- Virtual Channels (VC), Virtual output Que (VoQ)
- Interoperability what is realistic?
- Ethernet interworking
- Traffic Management -extensions





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Summary

- sRIO has been a key component in developing a multitude of advanced testbeds
- Facilitating re-use of hw and sw
- sRIO more flexible and easy to use than expected
- Wishlist: 2X, 6Gbit/s -> 10 Gbit/s
- Interoperability

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Some experiences from actually using sRIO

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Backup

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Flow Control Arbitration

- Extends the existing Type 7 congestion management packet functionality defined for flow level control
- Allows endpoints to manage and arbitrate for resource Segmentation and Reassembly (SAR) contexts at a PDU level
- Prevents traffic from being admitted to the fabric if there are no receiving end resources
- Endpoint wishing to transmit data sends Request message for single or multiple PDUs
- Receiving device allocates (Xon) or de-allocates (Xoff)
- Allows pipeline of request and TX Release message to de-allocate resources

Traffic Management

- Allows endpoints to coordinate traffic flows between class and stream based queues
- Uses the extended header type 9 packet format
 - Offers finer granularity control than type 7
- Receiving device sends messages to the transmitting device to throttle traffic
- Supports On/Off, Rate based, and Credit based schemes
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Encapsulation

Standard has three parts:

- Advertising participation in messaging scheme
 - Capabilites such as conveyance, mailbox ID, StreamID, COS
- Session Management Protocol
 - Discovering how to communicate
 - Identify protocols available and attributes about the protocols
- Encapsulation Format

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